

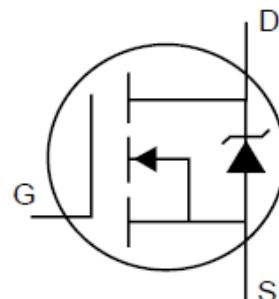
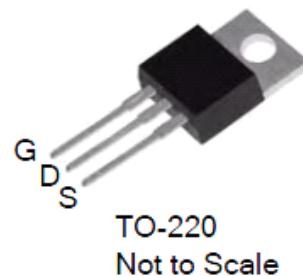
DESCRIPTION

The 8850 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

V_{DSS}	$R_{DS(ON)}$	I_D
88V	14mΩ	50A

GENERAL FEATURES

- $V_{DS} = 88V, I_D = 50A$
- $R_{DS(ON)} < 16m\Omega @ V_{GS}=10V$ (Typ: 14mΩ)
- High density cell design for ultra low Rdson.
- Fully characterized avalanche voltage and current.
- Special designed for Convertors and power controls .
- Good stability and uniformity with high EAS .
- Excellent package for good heat dissipation .
- Special process technology for high ESD capability .



Applications

- Power switching application.
- Hard switched and high frequency circuits.
- Uninterruptible power supply.

Ordering Information

PART NUMBER	PACKAGE	BRAND
8850	TO-220	0GFD

Absolute Maximum Ratings (TC=25°C, unless otherwise noted)

Symbol	Parameter	8850	Units
V _{DSS}	Drain-to-Source Voltage	80	V
I _D	Continuous Drain Current	50	
I _D (100°C)	Drain Current-Continuous(TC=100°C)	35.4	A
I _{DM}	Pulsed Drain Current@VG=10V	85	
P _D	Power Dissipation	110	W
	Derating Factor above 25 °C	0.73	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single PulseAvalanche Energy	450	mJ
T _J and T _{TSG}	Operating Junction and Storage Temperature Range	-55 to 175	°C

Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{θJC}	Junction-to-Case	--	--	1.36	°C/W	Water cooled heatsink, PD adjusted for a peak junction temperature of +175 °C.
R _{θJA}	Junction-to-Ambient	--	--	--		1 cubic foot chamber, free air.

OFF Characteristics TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
B _{VDS}	Drain-to-Source Breakdown Voltage	80	88	--	V	V _{GS} =0, I _D =250uA
I _{GSS}	Gate-to-Source Forward Leakage	--	--	±100	nA	V _{DS} =0V, V _{GS} =±20V
I _{DSS}	Zero Gate Voltage Drain Current	--	--	1	uA	V _{DS} =80V, V _{GS} =0V

ON Characteristics TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{DSON}	Static Drain-to-Source On-Resistance	--	14	16	mΩ	V _{GS} =10V, I _D =20A
V _{GS(TH)}	Gate Threshold Voltage, Figure 12.	2	3	4	V	V _{DS} =10V, I _D =250uA
G _{fS}	Forward Transconductance	28	---	--	S	V _{DS} =10V, I _D =20A

Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
C_{iss}	Input Capacitance	--	2350	--	pF	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$
C_{oss}	Output Capacitance	--	337	--		
C_{rss}	Reverse Transfer Capacitance	--	165	--		
Q_g	Total Gate Charge	--	34	--	nC	$V_{DS}=40V, V_{GS}=10V,$ $I_D=20A$
Q_{gs}	Gate-to-Source Charge	--	13	--		
Q_{gd}	Gate-to-Drain ("Miller") Charge	--	11	--		

Resistive Switching Characteristics Essentially independent of operating temperature

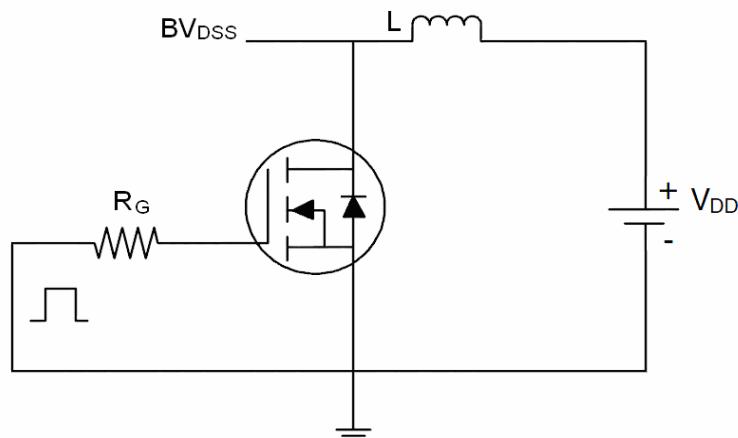
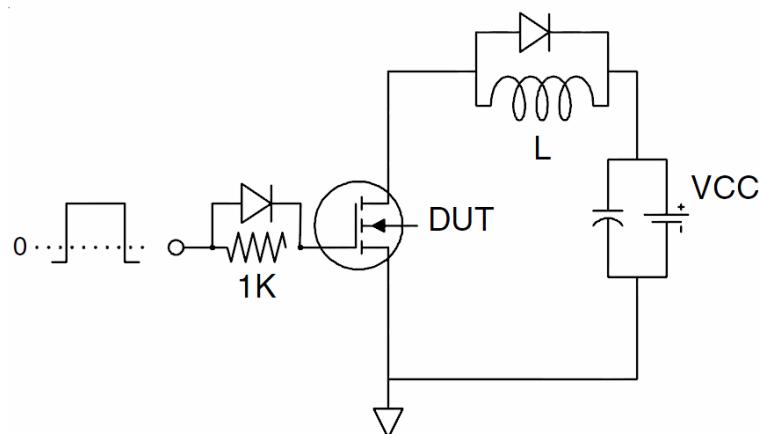
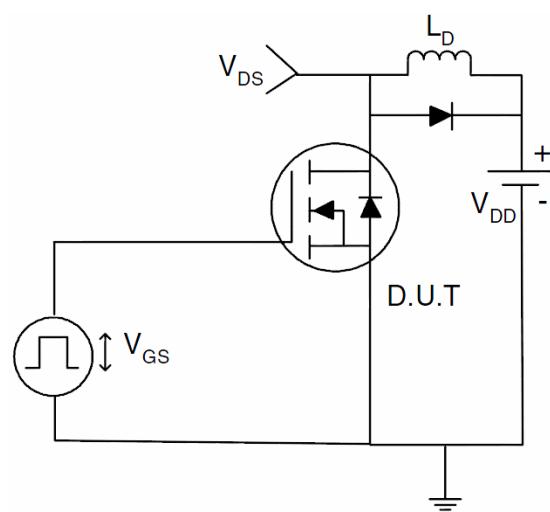
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$T_{d(ON)}$	Turn-on Delay Time		12		ns	$VDD=40V, ID=2A,$ $RL=2\Omega$ $VGS=10V, RG=3\Omega$
T_{rise}	Rise Time		9			
$T_{d(OFF)}$	Turn-Off Delay Time		20			
T_{fall}	Fall Time		18			

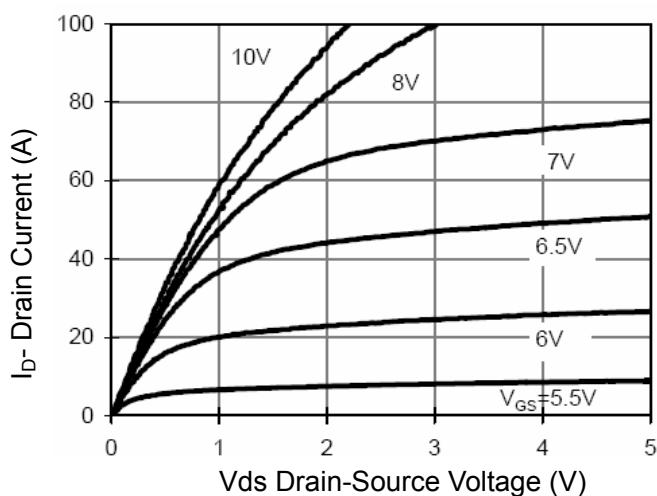
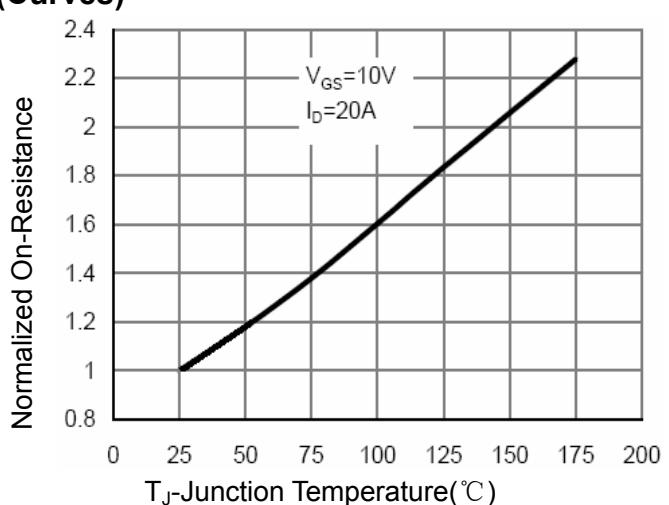
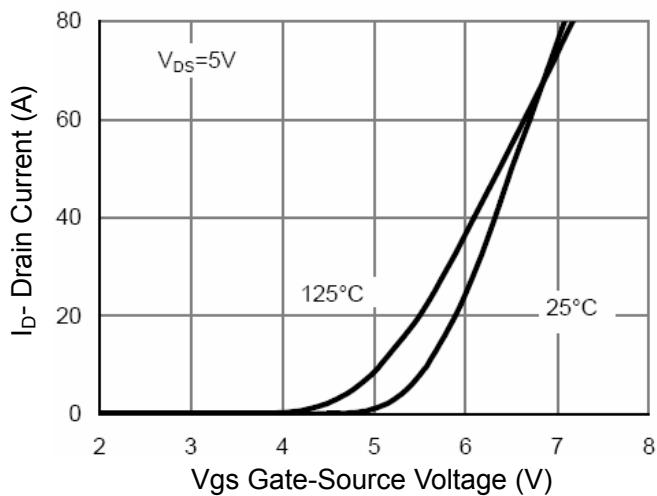
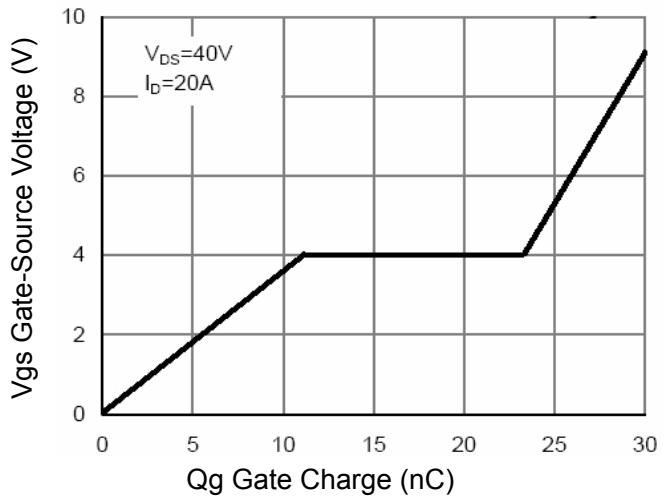
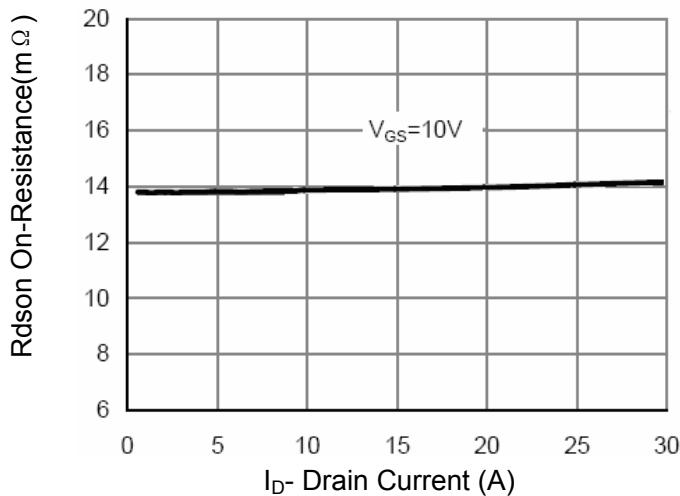
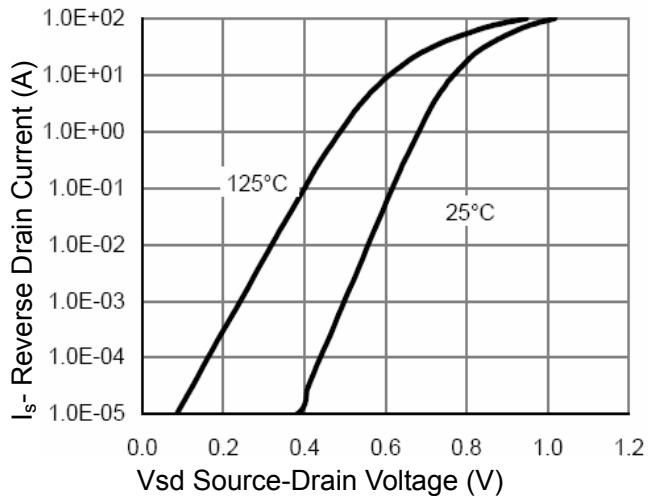
Drain-Source Diode Characteristics

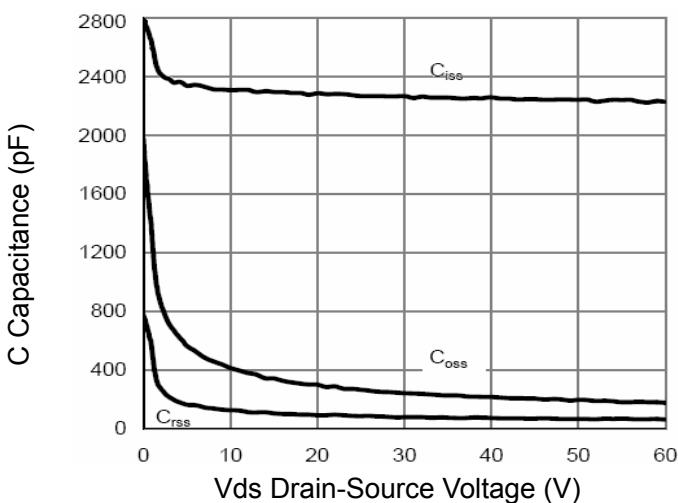
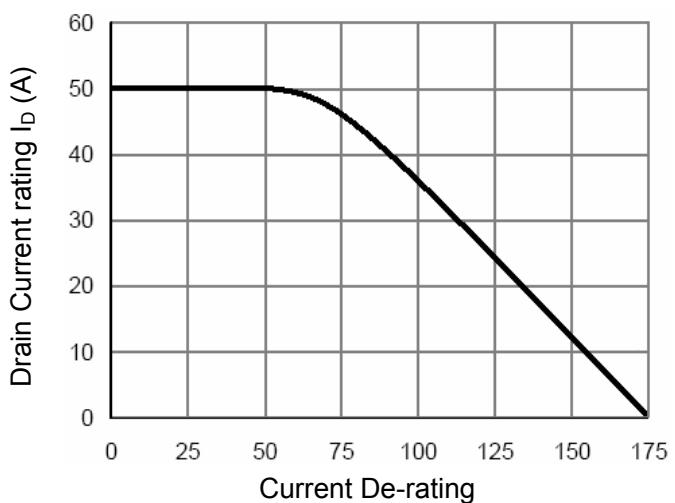
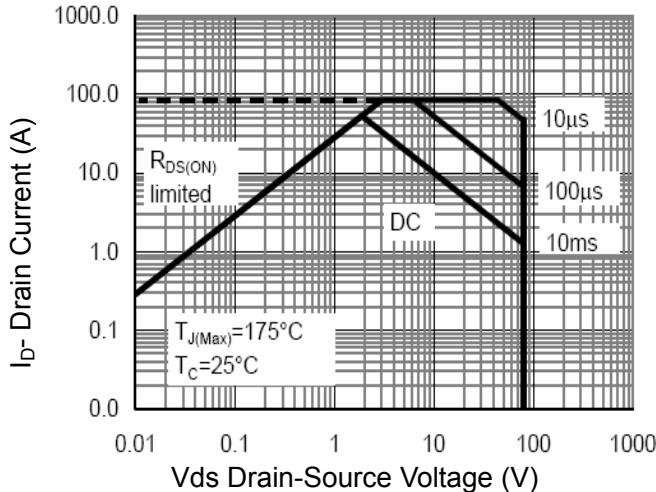
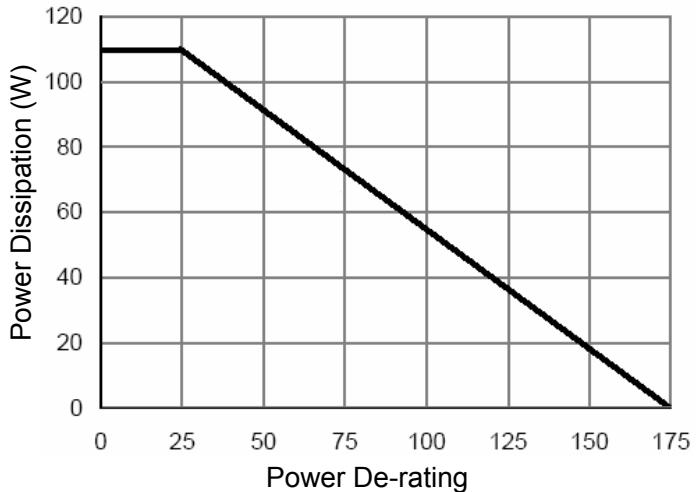
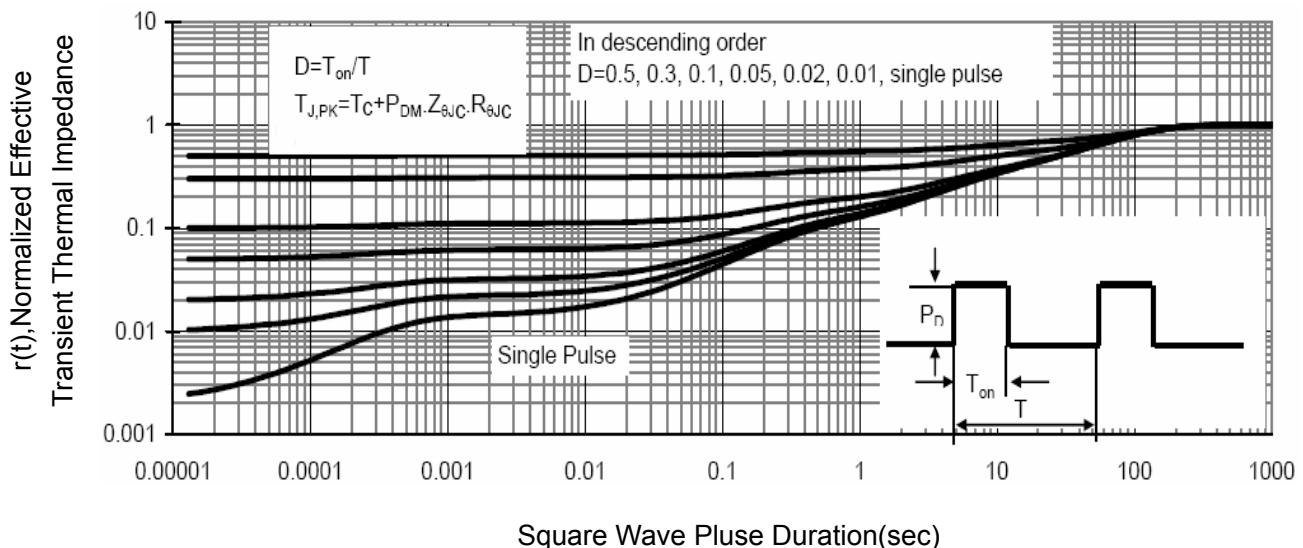
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=20A$	--	--	1.2	V	
Diode Forward Current	I_S	--	--	--	50	A	
Reverse Recovery Time	t_{rr}	$T_J=25^{\circ}C, IF=20A$ $Di/dt = 100 A/\mu s$	--	21	--	nS	
Reverse Recovery Charge	Q_{rr}		--	65	--	nC	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)					

Notes:

1. Repetitive Rating:Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test:Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production.
5. EAS condition: $T_j=25^{\circ}C, VDD=40V, V_G=10V, L=0.5mH, R_g=25\Omega$

Test Circuit**1) E_{AS} test Circuits****2) Gate charge test Circuit****3) Switch Time Test Circuit**

Typical Electrical and Thermal Characteristics (Curves)**Figure 1 Output Characteristics****Figure 4 Rdson-Junction Temperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9 Drain Current vs Junction Temperature****Figure 8 Safe Operation Area****Figure 10 Power vs Junction Temperature****Figure 11 Normalized Maximum Transient Thermal Impedance**

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